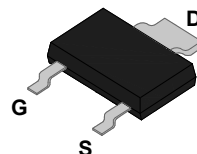
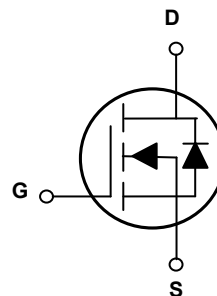


Main Product Characteristics

BV_{DSS}	700V
$R_{DS(ON)}$	1300mΩ
I_D	4A



SOT-223



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFL7004 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage ($V_{GS}=0\text{V}$)	V_{DS}	700	V
Gate-Source Voltage ($V_{DS}=0\text{V}$), AC ($f>1\text{ Hz}$)	V_{GS}	± 30	V
Drain Current-Continuous ($T_C=25^{\circ}\text{C}$)	$I_{D(DC)}$	4	A
Drain Current-Continuous ($T_C=100^{\circ}\text{C}$)		2.5	A
Drain Current-Pulsed ¹	I_{DM}	16	A
Power Dissipation ($T_C=25^{\circ}\text{C}$)	P_D	5.2	W
Single Pulse Avalanche Energy ²	E_{AS}	27	mJ
Avalanche Current ¹	I_{AR}	0.7	A
Repetitive Avalanche energy, t_{AR} Limited by T_{Jmax} ¹	E_{AR}	0.1	mJ
Drain Source Voltage Slope, $V_{DS}\leq 480\text{V}$	dv/dt	50	V/nS
Reverse Diode dv/dt , $V_{DS}\leq 48\text{ V}$, $I_{SD}<I_D$		15	
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	24	$^{\circ}\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	$^{\circ}\text{C/W}$
Storage Temperature Range	T_{STG}	-55 To +150	$^{\circ}\text{C}$
Operating Junction Temperature Range	T_J	-55 To +150	$^{\circ}\text{C}$

Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On/Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	700	-	-	V
Zero Gate Voltage Drain Current (T _C =25°C)	I _{DSS}	V _{DS} =700V , V _{GS} =0V	-	-	1	μA
Zero Gate Voltage Drain Current (T _C =125°C)			-	-	50	μA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	3	-	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =2A	-	1100	1300	mΩ
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =50V, V _{GS} =0V, F=1MHz	-	304	-	pF
Output Capacitance	C _{oss}		-	17	-	
Reverse Transfer Capacitance	C _{rss}		-	0.5	-	
Total Gate Charge	Q _g	V _{DS} =480V, I _D =4A, V _{GS} =10V	-	8.8	12	nC
Gate-Source Charge	Q _{gs}		-	2.3	-	
Gate-Drain Charge	Q _{gd}		-	4	-	
Switching Times						
Turn-On Delay Time	t _{d(on)}	V _{DD} =380V, R _G =5Ω V _{GS} =10V, I _D =2.5A	-	8	-	nS
Turn-On Rise Time	t _r		-	4	-	
Turn-Off Delay Time	t _{d(off)}		-	52	70	
Turn-Off Fall Time	t _f		-	9	18	
Source-Drain Diode Characteristics						
Source-Drain Current (Body Diode)	I _{SD}	T _C =25°C	-	-	4	A
Pulsed Source-Drain Current (Body Diode)	I _{SM}		-	-	16	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _{SD} =4A, T _J =25°C	-	0.9	1.2	V
Reverse Recovery Time	T _{rr}	I _F =2A, di/dt=100A/μs, T _J =25°C	-	200	-	nS
Reverse Recovery Charge	Q _{rr}		-	0.6	-	nC
Peak Reverse Recovery Current	I _{rrm}		-	6	-	A

Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. $T_J=25^{\circ}\text{C}, V_{DD}=50V, V_G=10V, R_G=25\Omega$

Typical Electrical and Thermal Characteristic Curves

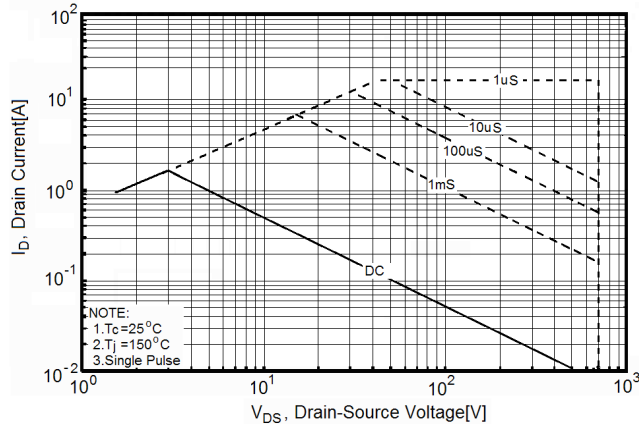


Figure 1. Safe Operating Area

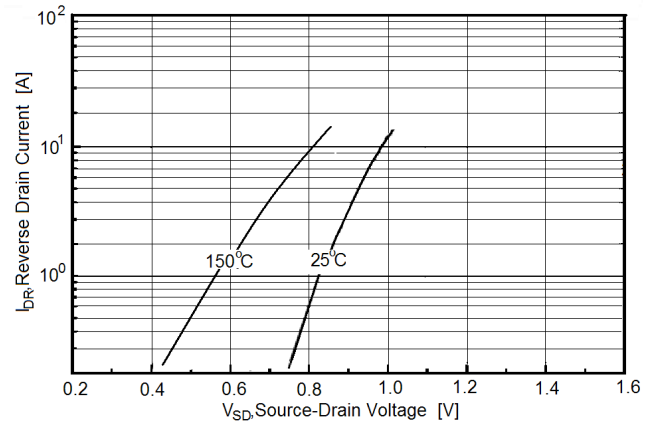


Figure 2. Source-Drain Diode Forward Voltage

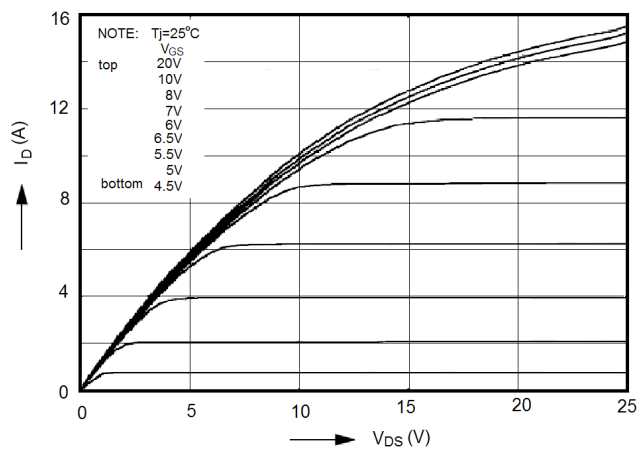


Figure 3. Output Characteristics

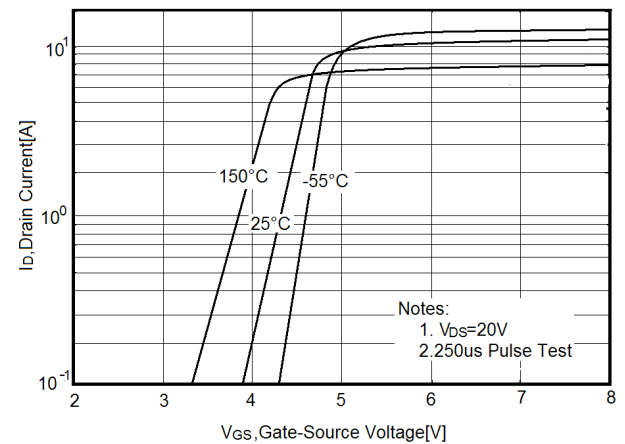


Figure 4. Transfer Characteristics

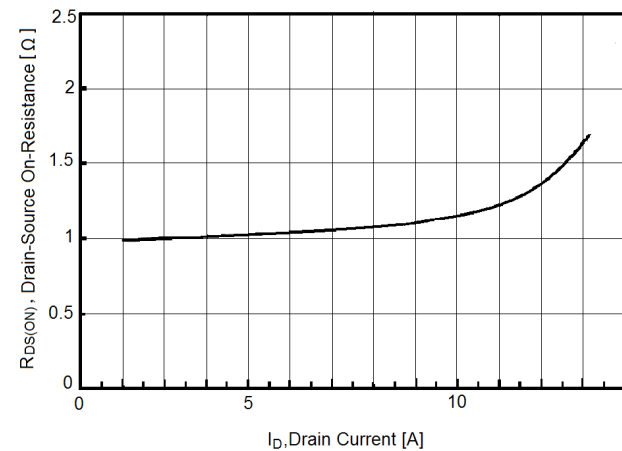


Figure 5. Static Drain-Source on Resistance

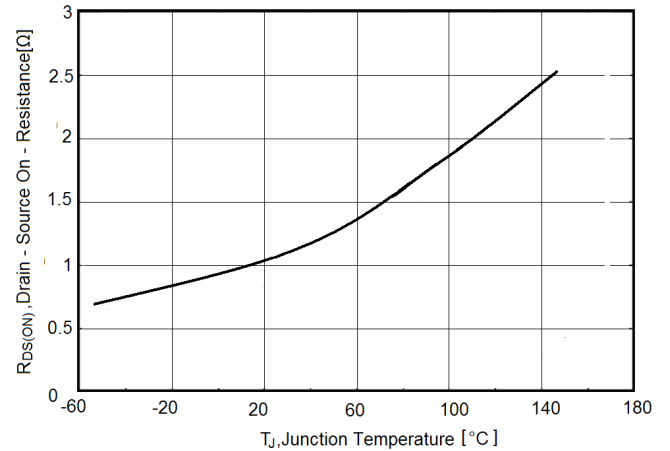


Figure 6. $R_{DS(ON)}$ vs Junction Temperature

Typical Electrical and Thermal Characteristic Curves

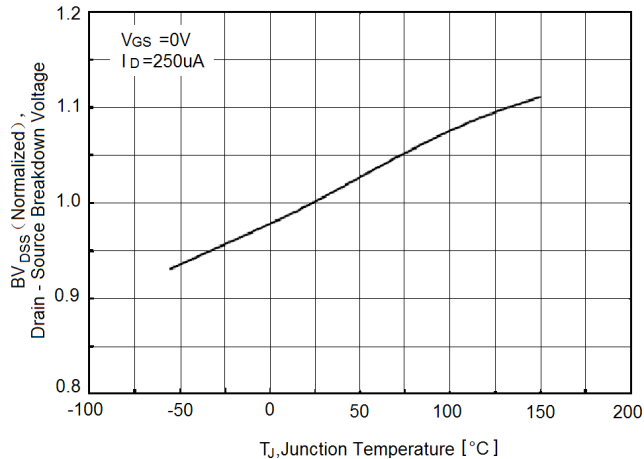


Figure 7. BV_{DSS} vs Junction Temperature

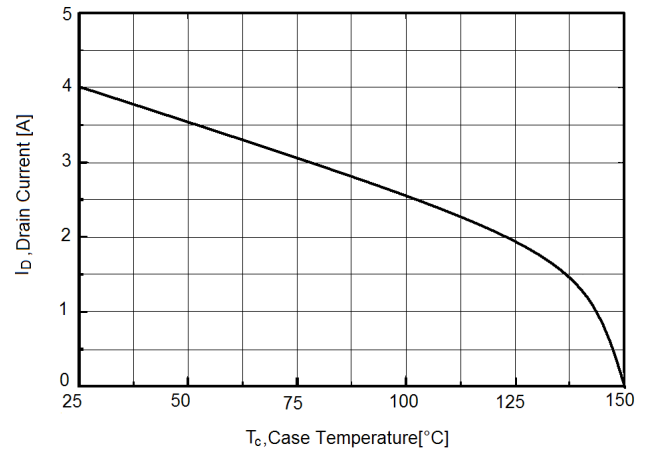


Figure 8. Maximum I_D vs Junction Temperature

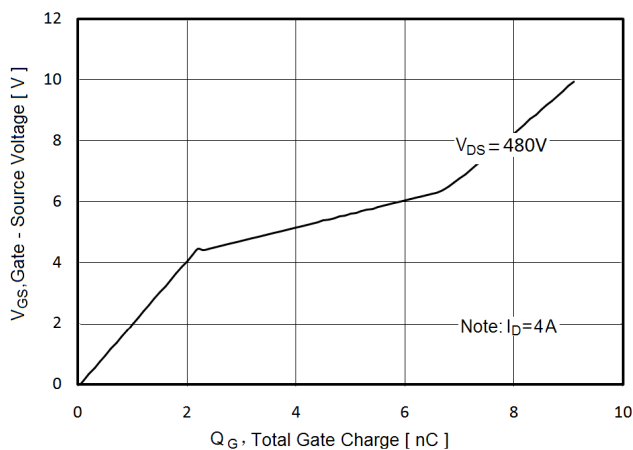


Figure 9. Gate Charge Waveforms

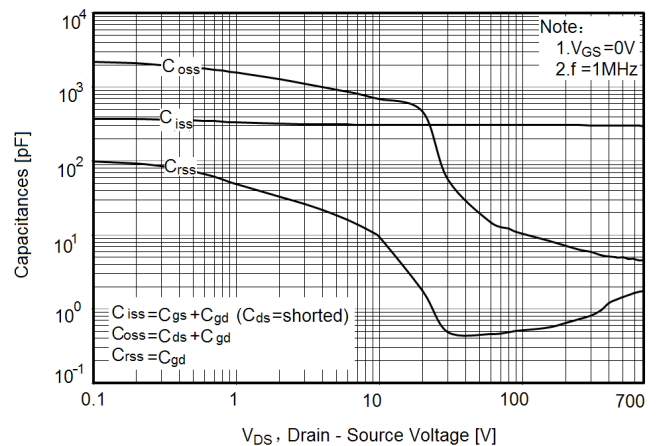


Figure 10. Capacitance

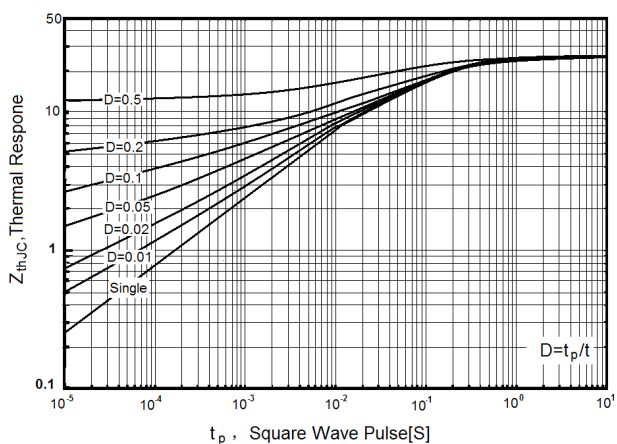


Figure 11. Transient Thermal Impedance

Typical Electrical and Thermal Characteristic Curves

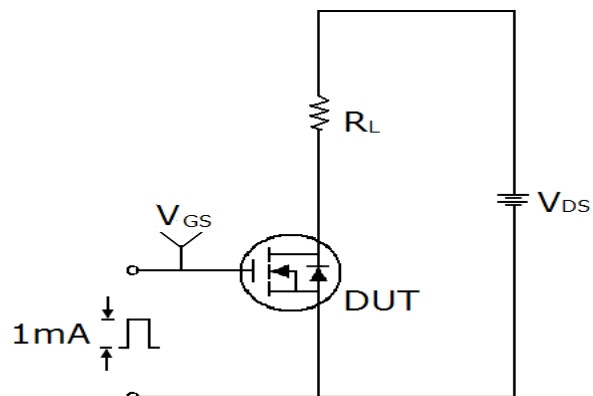


Figure 12. Gate Charge Test Circuit & Waveform

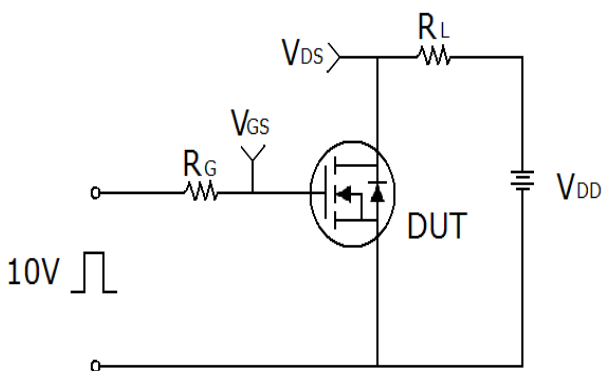
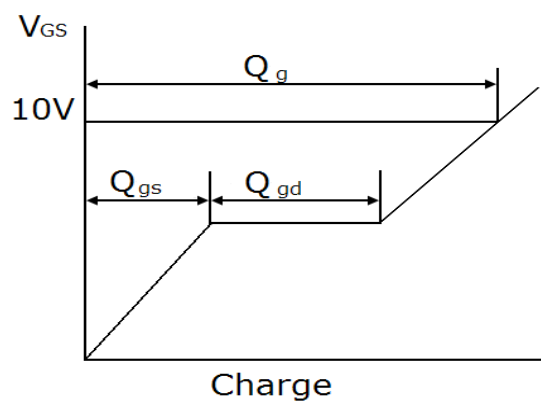


Figure 13. Switch Time Test Circuit

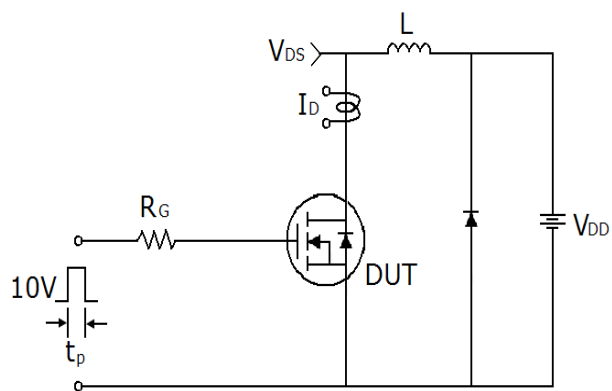
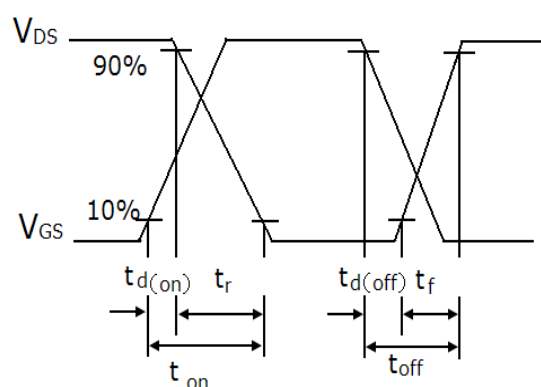
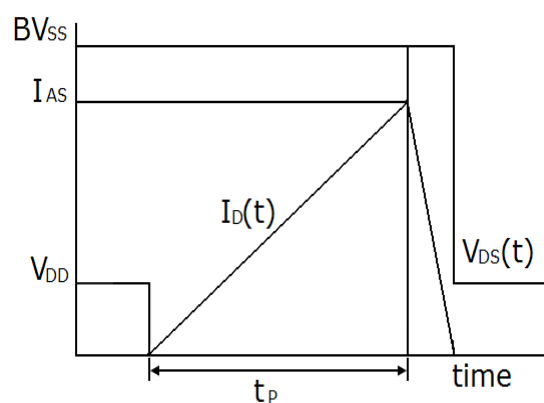
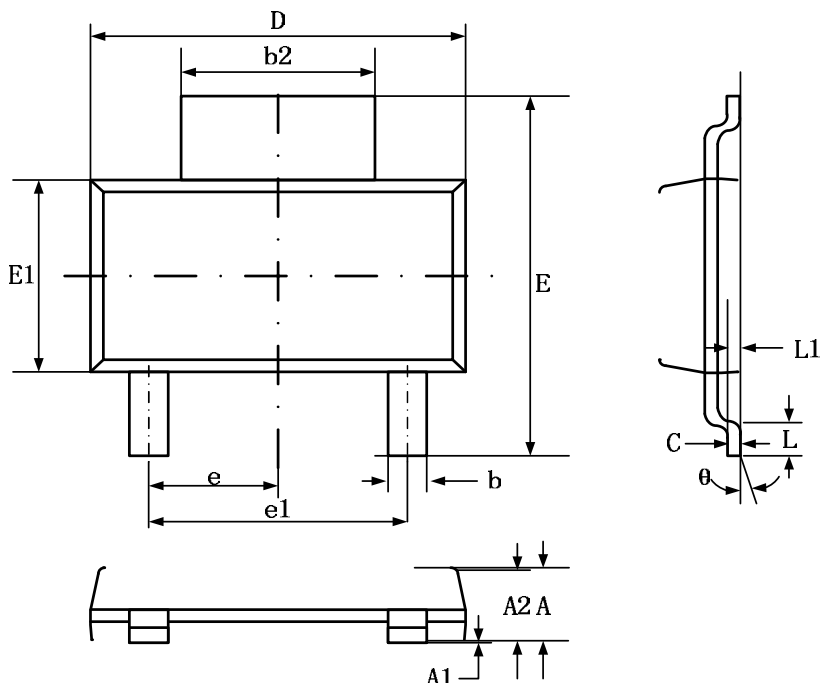


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Package Outline Dimensions (SOT-223)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	—	1.80	—	0.071
A1	0.02	0.10	0.001	0.004
A2	1.50	1.70	0.059	0.067
b	0.66	0.84	0.026	0.033
b2	2.90	3.10	0.114	0.122
c	0.23	0.35	0.009	0.014
D	6.30	6.70	0.248	0.264
E	6.70	7.30	0.264	0.287
E1	3.30	3.70	0.130	0.146
e	2.30 BSC.		0.091 BSC.	
e1	4.60 BSC.		0.182 BSC.	
L	0.81	—	0.032	—
L1	0.25 BSC.		0.032 BSC.	
θ	0°	10°	0°	10°